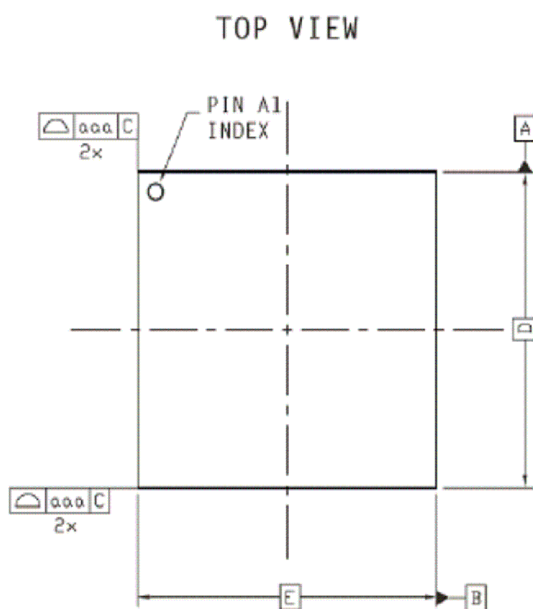
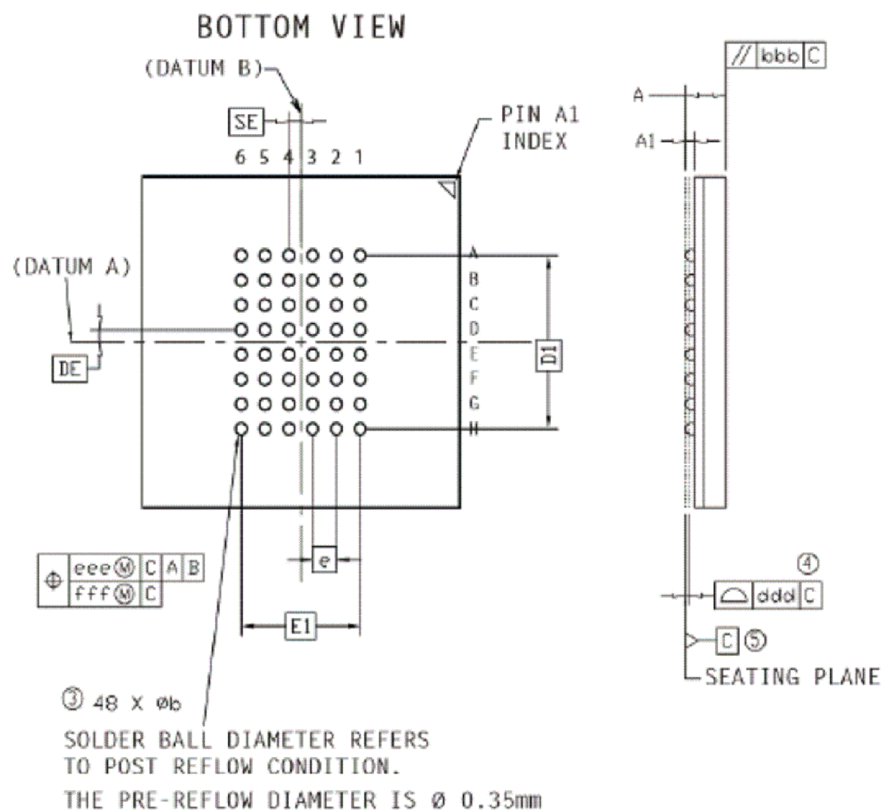
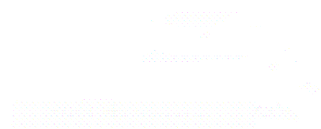


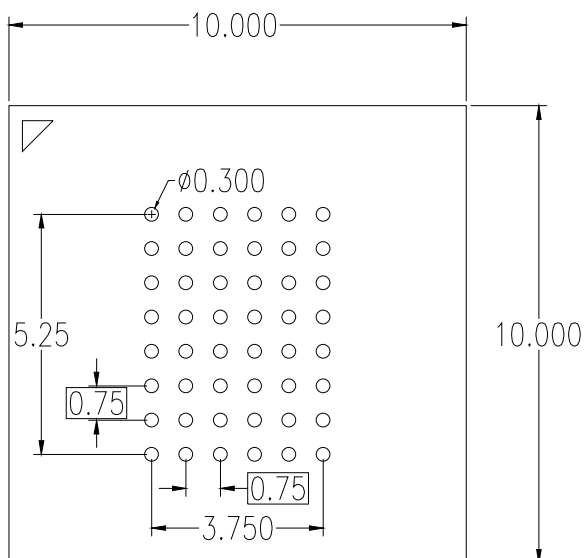


Ref	Min	Nominal	Max
A	1.19	1.27	1.35
A1	0.22	0.27	0.32
b	0.31	0.36	0.41
D	10.00 BSC		
E	10.00 BSC		
D1	5.25 BSC		
E1	3.75 BSC		
DE	0.375 BSC		
SE	0.375 BSC		
e	0.75 BSC		

Ref	Tolerance of, from and position
aaa	0.10
bbb	0.10
ddd	0.10
eee	0.15
fff	0.08



1. Dimensions in Millimeters.
2. The 'e' represents the basic solder ball grid pitch.
- ③ 'b' is measurable at the maximum solder ball diameter in a plane parallel to datum C.
- ④ Dimension 'ddd' is measured parallel to primary datum C.
- ⑤ Primary datum C (seating plane) is defined by the crowns of the solder balls.
6. Package dimensions refer to JEDEC MO-205 Rev. G.



RECOMMENDED LAND PATTERN DIMENSION

NOTES:

1. ALL DIMENSIONS ARE IN MM. ANGLES IN DEGREES.
2. TOP DOWN VIEW AS VIEWED ON PCB.
3. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN
4. SMD PATTERN ASSUMED

Package Revision History		
Date Created	Rev No.	Description
July 12, 2022	02	Update Land Pattern Dimension
July 20, 2020	01	Add Recommended Land Pattern